

20V N-Channel Enhancement Mode MOSFET

Description

The NP2302FVR uses advanced trench technology to provide excellent $R_{\text{DS(ON)}}$, low gate charge and high density cell Design for ultra low on-resistance. This device is suitable for use as a load switch or in PWM applications.

General Features

ightharpoonup V_{DS} =20V, I_D =2A

 $\begin{array}{ll} R_{DS(ON)}(Typ.){=}40m\Omega & @V_{GS}{=}4.5V \\ R_{DS(ON)}(Typ.){=}50m\Omega & @V_{GS}{=}2.5V \end{array}$

- High power and current handing capability
- ◆ Lead free product is acquired
- Surface mount package

Application

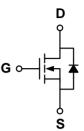
- PWM applications
- Load switch

Package

♦ SOT-23

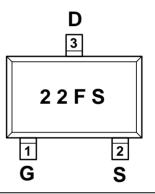


Schematic diagram



Marking and pin assignment

SOT-23 (TOP VIEW)



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP2302FVR-YB-G	-55°C to +150°C	SOT-23	3000

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V _{DS}	20	V
Gate-source voltage	V _{GS}	±12	V
Drain current-continuous ^a @Tj=125℃	I _D	2	Α
-pulse d^b	I _{DM}	8	Α
Drain-source Diode forward current	Is	2	Α
Maximum power dissipation	P _D	1.25	W
Operating junction Temperature range	Tj	-55—150	$^{\circ}$



Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit			
OFF Characteristics									
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	20	-	-	V			
Zero gate voltage drain current	I _{DSS}	I _{DSS} V _{DS} =20V, V _{GS} =0V		-	1	μΑ			
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA			
	ON Characteristics								
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.75	1.2	V			
	Б	V _{GS} =4.5V, I _D =2A	-	40	50	m (
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =2.5V, I _D =1A		50	60	mΩ			
Forward transconductance	gfs	V _{GS} =5V, I _D =2A	-	5	-	S			
	Dynamic C	Characteristics			•	<u> </u>			
Input capacitance	C _{ISS}		-	180	-	pF			
Output capacitance	Coss	V _{DS} =10V ,V _{GS} =0V f=1.0MHz	-	38	-				
Reverse transfer capacitance	C _{RSS}	1-1.01/11/12	-	20	-				
Switching Characteristics									
Turn-on delay time	t _{D(ON)}	101/	-	8	-				
Rise time	tr	$V_{DD}=10V$ $R_L=3$ ohm	-	7	-				
Turn-off delay time	t _{D(OFF)}	V _{GEN} =4.5V	-	30	-	ns			
Fall time	tf	R _{GEN} =6ohm	-	7	-				
Total gate charge	Qg	V _{DS} =10V	-	3.5	-				
Gate-source charge	Qgs	I _D =3A	-	0.6	-	nC			
Gate-drain charge	Qgd	V _{GS} =4.5V	-	0.45	-				
DRAIN-SOURCE DIODE CHARACTERISTICS									
Diode forward voltage	V _{SD}	V _{GS} =0V,Is=3A	-	0.76	1.16	V			

Notes:

- a. surface mounted on FR4 board,t≤10sec
- b. pulse test: pulse width≤300µs,duty≤2%
- c. guaranteed by design, not subject to production testing

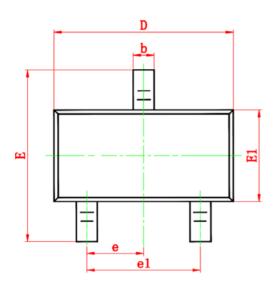
Thermal Characteristics

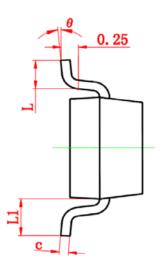
Thermal Resistance junction-to ambient	$R_{\theta JA}$	100	°C/W
--	-----------------	-----	------

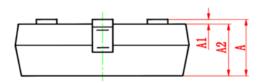


Package Information

• SOT-23







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	2.250	2.550	0.089	0.100	
E1	1.200	1.400	0.047	0.055	
е	0.950 TYP.		0.037 TYP.		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.500	0.012	0.020	
L1	0.550 REF.		0.022 REF.		
θ	0°	8°	0°	8°	